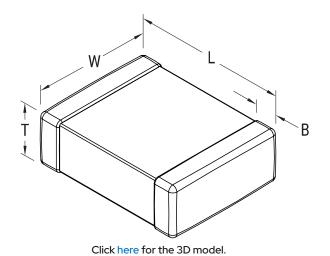


CBR02C649D3GAC

General Information

CBR-SMD RF COG, Ceramic, 6.4 pF, +/-0.5 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201



CBR-SMD RF COG Series Style SMD Chip Description SMD, Fixed, RF, Ultra High Q, Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 0.3 mg Notes Solder Reflow Only. Shelf Life 78 Weeks MSL 1

| Dimensions | |
|------------|------------------|
| Chip Size | 0201 |
| L | 0.6mm +/-0.03mm |
| W | 0.3mm +/-0.03mm |
| т | 0.3mm +/-0.03mm |
| В | 0.15mm +/-0.05mm |

15000

T&R, 180mm, Plastic Tape

| Packaging Specifications | |
|--------------------------|--|
| Packaging | |

Packaging Packaging Quantity Specifications Capacitance 6.4 pF Tolerance +/-0.5 pF Voltage DC 25 VDC **Dielectric Withstanding Voltage** 62.5 VDC -55/+125°C **Temperature Range** COG Temp. Coefficient 0.189% **Dissipation Factor** 0% Loss/Decade Hour Aging Rate Insulation Resistance 10 GOhms **Quality Factor** 528

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